



Product Change Notification

112094 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 112094 - 00
Change Title: Intel® True Scale Fabric Host Channel Adapter QLE7340CK, Intel® True Scale Fabric Host Channel Adapter QLE7340LCK, Intel® True Scale Fabric Host Channel Adapter QLE7342CK

PCN 112094-00, Manufacturing Site, Label, Product Marking

QLE734x Packaging and Labeling Changes for Manufacturer Site Change and RoHS II

Date of Publication: April 26, 2013

Key Characteristics of the Change:

Manufacturing Site, Label, Product Marking

Forecasted Key Milestones:

Date of Samples Availability:	May 01, 2013
Date Customer Must be Ready to Receive Post-Conversion Material:	May 01, 2013
Date of First Availability of Post-Conversion Material:	May 01, 2013

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Affected Product Code	Former Product Code	Product Description
QLE7342CK	IB6413601-03	Intel® True Scale Fabric Host Channel Adapter QLE7342CK
QLE7340CK	IB6413601-04	Intel® True Scale Fabric Host Channel Adapter QLE7340CK
QLE7340LCK	IB6413601-06	Intel® True Scale Fabric Host Channel Adapter QLE7340LCK

Overview of Changes



The labels and label contents for the listed products were revised for a manufacturing site change to Flextronics* Malaysia, due to the product line acquisition from QLogic* to Intel completed in 2012.

Labeling throughout the product was also updated to meet new marking requirements under RoHS II Directive 2011/65/EU Declaration of Compliance, effective 1/1/2013. This includes a requirement for a single point of contact address label for items requiring the "CE" mark.

Finally, clamshell packaging, cartons, and boxes were changed to use existing Intel designs and suppliers.

Change Details

- 1) On the unit PCBA, added Flextronics Malaysia manufacturing location prefix and updated unit serial number format to conform to existing two character Intel requirement for CM site code.

From	To
	
Where R = QLogic CM Site ID Where IB = QLogic InfiniBand Product ID	FM= Intel CM Site ID I= Intel Product ID

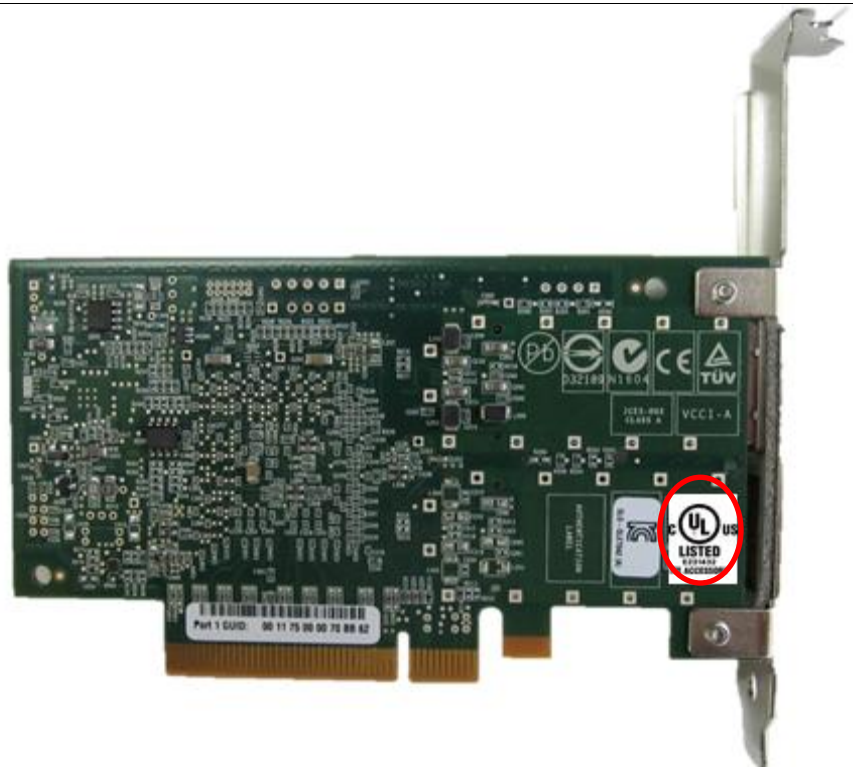
* Other names and brands may be claimed as the property of others.

- 2) On the unit PCBA, removed QLogic Authentication label and added updated UL mark with new Intel registration number, E231432.



From



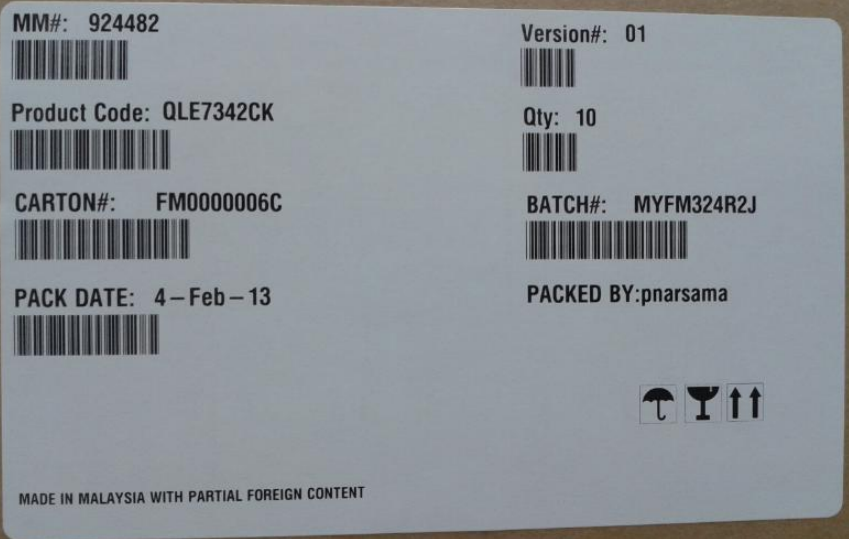
To





- 3) Over-pack carton label changes
- Replaced QLogic Model Number (Example: QLE7340-CK) with Intel MM number and revision for both barcode and human readable element.
 - Replaced Top Assembly Part Number (Example: IB6413601-04) with Intel Product Code for both barcode and human readable element.
 - Removed the No Lead and RoHS Compliant text element and added the European Commission CE mark with RoHS II Directive 2011/65/EU required manufacturer's address.
 - Removed QLogic name and logo mark.

From	To																																
 <p>QLOGIC MODEL NO QLE7430-CK P/N: IB6413601-04 APPLICANT QLOGIC CORPORATION DOM: 06/14/11 ASSEMBLED IN UNITED STATES</p> <p>RoHS COMPLIANT</p> <p>SERIAL NUMBER LIST</p> <table border="0"> <tr><td>AFD1119T99001</td><td>AFD1119T99002</td></tr> <tr><td>AFD1119T99003</td><td>AFD1119T99004</td></tr> <tr><td>AFD1119T99005</td><td>AFD1119T99006</td></tr> <tr><td>AFD1119T99007</td><td>AFD1119T99008</td></tr> <tr><td>AFD1119T99009</td><td>AFD1119T99010</td></tr> <tr><td>AFD1119T99011</td><td>AFD1119T99012</td></tr> <tr><td>AFD1119T99013</td><td>AFD1119T99014</td></tr> <tr><td>AFD1119T99015</td><td>AFD1119T99016</td></tr> <tr><td>AFD1119T99017</td><td>AFD1119T99018</td></tr> <tr><td>AFD1119T99019</td><td>AFD1119T99020</td></tr> </table>	AFD1119T99001	AFD1119T99002	AFD1119T99003	AFD1119T99004	AFD1119T99005	AFD1119T99006	AFD1119T99007	AFD1119T99008	AFD1119T99009	AFD1119T99010	AFD1119T99011	AFD1119T99012	AFD1119T99013	AFD1119T99014	AFD1119T99015	AFD1119T99016	AFD1119T99017	AFD1119T99018	AFD1119T99019	AFD1119T99020	 <p>INTEL CORPORATION MM#: 123456 Ver #: 12 Product Code #: 123456789012345 Applicant: 123456789012345 DOM: 1/8/13 MADE IN MALAYSIA</p> <p>CE Intel Corporation Attn: Corporate Quality 2200 Mission College Blvd Santa Clara, CA 95058-1149 USA</p> <p>SERIAL NUMBER LIST</p> <table border="0"> <tr><td>1234567890123</td><td>1234567890123</td></tr> <tr><td>1234567890123</td><td>1234567890123</td></tr> <tr><td>1234567890123</td><td>1234567890123</td></tr> <tr><td>1234567890123</td><td>1234567890123</td></tr> <tr><td>1234567890123</td><td>1234567890123</td></tr> <tr><td>1234567890123</td><td>1234567890123</td></tr> </table>	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123	1234567890123
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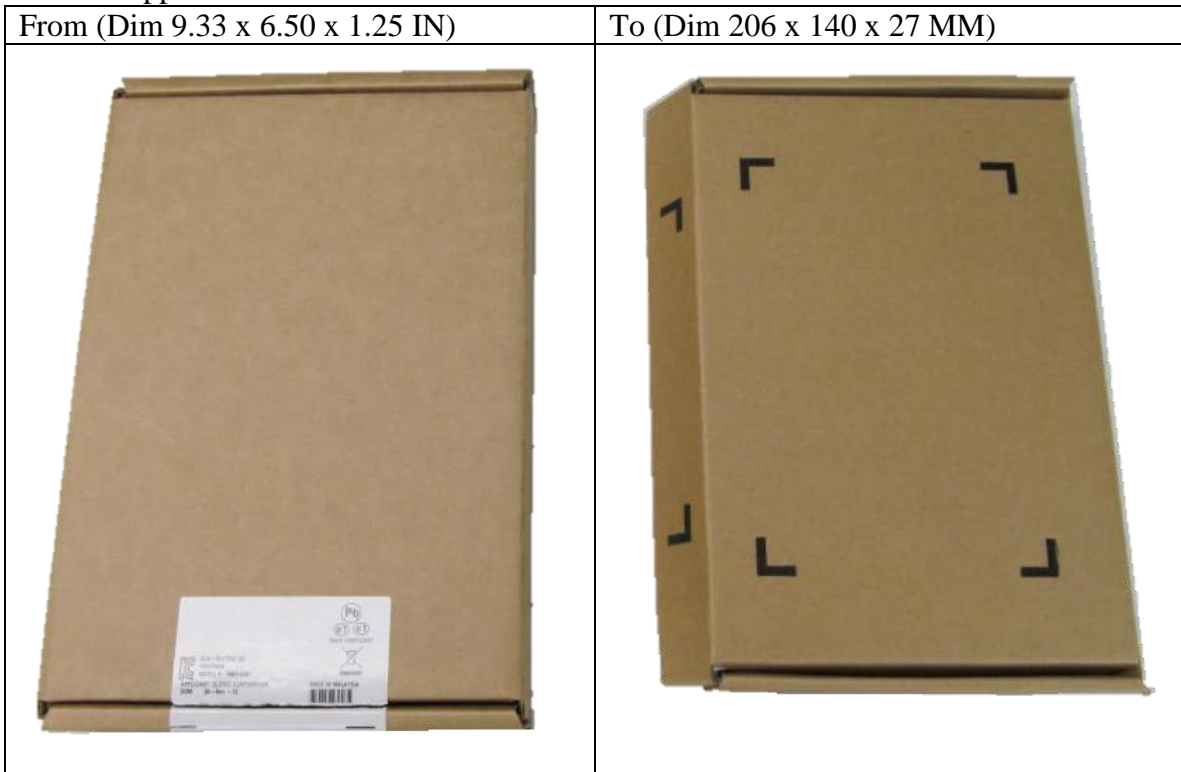
- Added new Intel Master Carton label to support internal shipping requirements.

From	To
Did not Exist	 <p>MM#: 924482 Version#: 01 Product Code: QLE7342CK Qty: 10 CARTON#: FM0000006C BATCH#: MYFM324R2J PACK DATE: 4 - Feb - 13 PACKED BY: pnarsama</p> <p>MADE IN MALAYSIA WITH PARTIAL FOREIGN CONTENT</p>

- 4) Changed clamshell packaging to use existing Intel design and supplier. Removed Part Number/ESD warning and QLogic Authentication closure label from clamshell container. RoHS elements required removal per RoHS II Directive 2011/65/EU marking requirements.

From	To
	

- 5) Changed single unit carton packaging to use existing Intel carton design and supplier.



- 6) Changed 10 count over-pack shipping box to use existing Intel carton design and supplier, and removed QLogic name and logo.



- 7) Removed option for 20 count over-pack box. Units will only ship in a maximum 10 count over-pack box.

8) Single pack carton label changes

- Added Korean KC compliance mark to the carton label for easier viewing. This mark was already present on the actual adapter.
- Removed the No Lead and RoHS Compliant text element and added the European Commission CE mark with RoHS II Directive 2011/65/EU required manufacturer's address.
- Replaced QLogic Model Number (Example: QLE7340-CK) with Intel MM number and revision (Example: 924483 01) for both the barcode and human readable element.
- Replaced Top Assembly Part Number and Revision (Example: IB6413601-04 E) with the Intel Product Code (Example: QLE7340CK) for both the barcode and human readable element.
- Removed QLogic listed UPC product code.
- Eliminated QLogic name and logo sealing tape.

From	To
 A photograph of a white label on a cardboard box. The label features the QLogic logo on the left and right sides. The central text includes: 'ASSEMBLED IN MALAYSIA', a 'Pb' symbol with 'RoHS COMPLIANT' below it, 'Model NO: QLE7340-CK', 'PIN & REV: IB6413601-04 E', and 'S/N: FMI1305F00653'. There are several barcodes on the label.	 A photograph of a white label on a cardboard box. The label features the CE mark at the top left, with 'Intel Corporation' and address '2200 Mission College Blvd, Santa Clara, CA 95054-1549 USA' to its right. Below the CE mark is the KC mark and 'QLG - QLE7342 (A) InfiniBand MODEL #: IB6410401'. To the right is a crossed-out symbol and 'MADE IN MALAYSIA'. Further down, it lists 'APPLICANT: QLOGIC CORPORATION' and 'DOM: 02/04/13'. At the bottom, it shows 'MM#: 924482', 'Version#: 01', 'Product Code: QLE7342CK', and 'S/N: FMI1305F00653'. There are several barcodes on the label.

Customer Impact of Change and Recommended Action:

No impacts to fit or function. Minor impacts to form as visible branding, labeling, and packaging changes.

There is no change to the Intel MM Number.

Please contact your local Intel Field Sales Representative if you have any further questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change Top Assembly	Post Change Top Assembly
QLE7342CK	924482	IB6413601-03 Rev F	IB6413601-03 Rev G
QLE7340CK	924483	IB6413601-04 Rev E	IB6413601-04 Rev F
QLE7340LCK	924486	IB6413601-06 Rev D	IB6413601-06 Rev E

PCN Revision History:

Date of Revision:
April 26, 2013

Revision Number:
00

Reason:
Originally Published PCN